


MATERIAL DECLARATION SHEET



Reliable Electronic Solutions

Material #	CD216A Series	
Product Line	Integrated Passive & Active Devices	
Date	8/2/2004	
RoHS Compliant	Yes	

COMPONENT DETAILS

No.	Construction element	Material group	Material weight [g]	Materials	CAS if applicable	Average mass [%]	Sum [%]	Traces
1	Dice	Silicon with metal	0.00064	Si	7440-21-3	3.920	4	Al, B, P, Pt, Cu,
				Ni	7440-02-0	0.044		
2	High-melting point Solder paste	Tin-Lead solder	0.0008	Pb	7439-92-1	4.675	5	
				Sn	7440-31-5	0.250		
				Ag	7440-22-4	0.075		
3	Lead frame & clip	Copper alloy	0.00656	Cu	7440-50-8	40.07	41	Zn,P
				Fe	7439-89-6	0.873		
4	Mold compound	Epoxy material	0.0077	Silica(SiO2)	7631-86-9	33.69	48.12	
				Epoxy resin	68928-70-1	9.625		
				Sb2O3	1309-64-4	2.406		
				Phenolic resin	29690-82-2	2.406		
5	Plating cover	Tin solder	0.00016	Sn	7440-31-5	1	1	
		Total weight	0.016					

Lead Part Number Example: CD216A-B120R
 Pb Free Part Number Example: CD216A-B120RLF

Note: Avg. mass and sum data is a % of the component weight.
 It is the responsibility of the user to ensure that the latest revision is being accessed on the website.